

16th European Passive Components Conference

CARTS-EUROPE 2002

**14th - 17th October 2002
Holiday Inn Resort
Port St. Laurent, France**

Sponsored by
Electronic Components Institute Internationale Ltd.
in cooperation with
IMAPS - International Microelectronics And Packaging Society
EIA/ECA – Electronic Components, Assemblies, Equipment & Supplies Association
and
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PROGRAMME

Tuesday, 15th October

Welcome and Awards 09:00 - 09:10

Keynote:

Passive Components: A Metamorphosis; 09:10 - 09:40

Glyndwr Smith, Assistant fo CEO and Senior VP, Vishay ----- 1

Session 1: Niobium Capacitors 09:40 - 12:00

Chairman: Hugh Tyler, Cabot Corp.

1.1 *Niobium Oxide Technology Roadmap;*
T. Zednicek, S. Zedincek, Z. Sita, AVX Czech Rep.; W. Millman, J. Gill, AVX Ltd. ----- 11

1.2 *DC Bias Voltage Dependence of Anodized Niobium;*
M. Stenzel, H. Zillgen, EPCOS AG; K. Kovacs, G. Kiss, Budapest University of Technology. ----- 15

1.3 *Niobium Capacitors: From Raw Materials to Finished Parts;*
Y. Pozdeev-Freeman, Vishay Sprague. ----- 19

1.4 *New Niobium Based Materials for Solid Electrolyte Capacitors;*
C. Schnitter, U. Merker, A. Michaelis, H.C. Starck GmbH. ----- 26

1.5 *Charge Carriers Transport and Noise of Niobium Capacitors;*
J. Sikula, J. Pavelka, L. Grmela, P. Dobis, Czech Noise Research Lab;
Z. Sita, T. Zednicek, B. Vrana, AVX Czech Republic. ----- 32

1.6 *Panel Disucssion on Niobium, Speaker*

Session 2: Design and Construction 14:00 - 17:20

Chairman: Dan Persico, Kemet Electronics

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B. Stevenson, Greatbatch - Sierra Inc. USA. ----- 39

2.2 *Advances in Tantalum Capacitor Manufacturing Technology that will Enable the Continued Miniaturization of Electronic Designs;* D. Huntington, J. Gill, T. Zednicek, AVX Ltd. ----- 53

2.3 *How Low Can You Go - Tantalum Polymer Capacitors with ESR under 7 mΩ;*
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2.4 *Aluminum Anode Foil for Low Voltage Electrolytic Capacitors;*
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2.5 *PEDT as Conductive Polymer Cathode in Electrolytic Capacitors;*
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2.6 *Thin Film-High Density Interconnect Design Guidelines;*
W. CuvIELlo, D. Coulton, Vishay Electro-Films Inc. ----- 77

2.7 *New High Frequency Integrated Silicon Capcitor for High Q and Beyond 10 Gigahertz;*
H. Goldberger, T. Troianello, Vishay Intertechnology. ----- 88

Reception and Exhibits 18:00 - 19:30

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Session 3: Applications

08:30 - 12:00

Chairman: Knud Blohm, Danfoss A/S

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- 3.2 *Thermal Runaway of Tantalum Capacitors;*
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- 3.3 *Parameters Determination of Electrolytic Capacitor Model by Genetic Algorithm;* F. Perisse,
P. Venet, J. Retif, G. Rojat, Universite Claude Bernard Lyon. ----- 107
- 3.4 *Improvements in EMI/ESD Filtering of Integrated Multilayer Ceramic Components;*
T. Feichtinger, G. Grier, M. Ortner, G. Engel, EPCOS OHG. ----- 111
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Chairman: Reiner Keuhl, BCcomponents BEYSCHLAG GmbH

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